

LTM4619 144LD 15mm X 15mm X 2.82mm (TABLE OF MATERIAL DECLARATION)

The LTM4619 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2259	Barium Compounds	7727-43-7	0.00325	1.4400
				Filler Substances (Silica Crystalline)	13776-74-4, 7631-86-9	0.06772	29.9800
				Copper Metal	7440-50-8	0.08547	37.8350
				Copper Compounds	1328-53-6	0.00005	0.0230
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.0030
				Gold metal or alloy	7440-57-5	0.00088	0.3900
				Nickel	7440-02-0	0.00569	2.5200
				Zinc	7440-66-6	0.00007	0.0320
				Bismaleimide/Triazine Resin	non-disclosure	0.05320	23.5500
				Acrylic Resin	non-disclosure	0.00703	3.1100
				Epoxy Resin	non-disclosure	0.00012	0.0550
				Chromium(III) Oxide	1308-38-9	0.00000	0.0010
				Silica Crystalline	14808-60-7	0.00084	0.3700
				Talc; not containing fibers like asbestors	14807-96-6	0.00043	0.1900
				Aromatic carbonyl compounds	non-disclosure	0.00072	0.3190
				Cyanoguanidine	461-58-5	0.00001	0.0060
				Amine compounds	non-disclosure	0.00012	0.0510
				Leveling agent and others	non-disclosure	0.00027	0.1200
				Imidazole system curing reagent	non-disclosure	0.00001	0.0050
2	Solder Paste	Alloy	0.0592	Sn	7440-31-5	0.05624	95.0000
				Sb	7440-36-0	0.00296	5.0000
3	Passive/Active Components		0.4920	Iron Powder (Fe)	7439-89-6	0.32683	66.4279
				Copper (Cu)	7440-50-8	0.10420	21.1780
				Nickel (Ni)	7440-02-0	0.00724	1.4713
				Tin (Sn)	7440-31-5	0.00455	0.9248
				Ceramic (Ba) Compounds	12047-27-7	0.04919	9.9980
4	Active Ics	Silicon	0.0067	Silicon	7440-21-3	0.00670	100.0000
5	Wire	Gold	0.0013	Au	7440-57-5	0.00130	99.9900
6	Encapsulation	Epoxy Resin	0.9148	Fused Silica	60676-86-0	0.70623	77.2000
				Epoxy Resin	non-disclosure	0.08142	8.9000
				Phenol Resin	non-disclosure	0.08142	8.9000
				Crytalline Silica	14808-60-7	0.02744	3.0000
				Carbon Black	1333-86-4	0.00457	0.5000
				Metal Hydroxide	non-disclosure	0.01372	1.5000
				Total Package Weight			1.6999

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts